

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	998209	(substrate carrier substrate motherboard ((printed circuit wiring mother) adj4 board)) same (bond bonding terminal electrode pad paddle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/13 03:14
L2	1307534	(substrate carrier substrate motherboard ((printed circuit wiring mother) adj4 board)) same (bond bonding contact terminal electrode contpad paddle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/13 03:15
L3	589672	(chip die semiconductor ic (integrated adj circuit) flipchip (flip adj chip) element electronic microprocessor microelectronic) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/13 03:18
L4	44489	(bump ball bga) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/13 03:20
L5	124881	(packag\$4 assembly apparatus) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/13 03:21
L6	20921	(packag\$4 assembly apparatus) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/13 03:21
L7	2985	(semi semifinish\$4 unoccup\$4 available free open overly\$3) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/13 03:28
L8	1699	(via opening thu through throughhole) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/13 03:28